

ICS 25.160.50

CCS J 33



**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 38265.9-2022

**Test methods for soft soldering fluxes - Part 9: Determination of
ammonia content**

Issued on: October 12, 2022

Implemented on: October 12, 2022

**Issued by: State Administration for Market Regulation, China National
Standardization Administration**

Table of Contents

Preface	
Introduction	
1 Scope	1
2 Normative references	1
3 Terms and Definitions	1
4 Principle	1
5 Reagent	1
6 Instruments and equipment	2
7 Test Step	3
8 Experimental data processing	3
9 Precision	4
10 Test report	4
Appendix A (informative) Comparison between this document and ISO 9455-9.2020 structure number	5
Reference	6

foreword

This document is in accordance with the provisions of GB/T 1.1-2020 "Guidelines for Standardization Work Part 1. Structure and Drafting Rules for Standardization Documents" drafting.

This document is Part 9 of GB/T 38265 "Test Methods for Solder Flux". GB/T 38265 has released the following parts.

- Part 1. Gravimetric method for the determination of non-volatile matter content;
- Part 2. Determination of non-volatile matter content boiling point method;
- Part 3. Determination of acid value Potentiometric titration and visual titration;
- Part 5. Copper mirror test;
- Part 6. Determination of content of halides (excluding fluorides);
- Part 8. Determination of zinc content;
- Part 9. Determination of ammonia content;

- Part 10.Solder wetting performance spreading test method;
- Part 11.Solubility of flux residues;
- Part 13.Determination of flux splashing;
- Part 14.Evaluation of the adhesiveness of flux residues;
- Part 15.Copper corrosion test;
- Part 16.Solder wetting performance Wetting balance method;
- Part 17.Flux residue surface insulation resistance comb test and electrochemical migration test.

This document is modified to adopt ISO 9455-9.2020 "Test methods for soldering flux - Part 9.Determination of ammonia content".

Compared with ISO 9455-9.2020, this document has more structural adjustments. The structure number changes between the two documents are compared in the list

See Appendix A.

The technical differences between this document and ISO 9455-9.2020 and their reasons are as follows.

- Changed the calibration method of the reagent "sodium hydroxide solution (1.0mol/L)" (see 5.3) to adapt to the technical conditions of our country;
- Changed the calibration method of the reagent "sulfuric acid solution (0.5mol/L)" (see 5.4) to adapt to the technical conditions of our country;
- Changed the expression and preparation process of the reagent "methyl orange indicator solution (1g/L)" (see 5.5) to adapt to the technical conditions of our country;
- Increase the reference to GB/T 6379.2 (see Chapter 9) to adapt to my country's technical conditions and increase operability.

The following editorial changes have been made to this document.

- In order to coordinate with the existing standards, the name of the standard was changed to "Test methods for soldering flux Part 9.Determination of ammonia content";
- Replaced ISO 9454-1 with the informative referenced GB/T 15829 (see Chapter 1).

Introduction

As the key supporting combination material in the soldering process, soldering agent has a decisive influence on the quality of soldered joints.

The strong foundation project being implemented, the national science and technology

major project "core electronic devices, high-end general-purpose chips and basic software products" and "ultra-large-scale

Technology research and development of core electronic devices, high-end chips and integrated circuit complete sets of technology in the Special Project of Modular Integrated Circuit Manufacturing Equipment and Complete Processes

Among them, solder is the key basic material, and the formulation of test method standards for its quality performance evaluation is of great significance.

Since 2001, my country has promulgated and implemented GB/T 3131 "Sn-Lead Solder", GB/T 20422 "Lead-Free Solder",

GB/T 15829 "Classification and Performance Requirements of Solder Fluxes" and GB/T 28770 "Test Methods for Solder Materials" and other supporting standards, solder

As an important component of solder, solder not only has an important impact on the solderability and manufacturability of solder, but also affects the environment, the reliability of solder joints and

And application is also very important. GB/T 38265 "Test Methods for Soldering Fluxes" is the general test method standard for soldering fluxes. It is proposed to be composed of the following parts

constitute.

--- Part 1. Gravimetric method for the determination of non-volatile matter content. The purpose is to specify the use of gravimetric method to determine the non-volatile

Test method for substance content.

--- Part 2. Determination of non-volatile matter content Boiling point method. The purpose is to stipulate the determination of the non-volatile oil in solder by the boiling point method.

Test method for substance content.

--- Part 3. Determination of acid value potentiometric titration and visual titration. The purpose is to specify the use of potentiometric titration and visual titration

Standard test method for the determination of acid value in solder.

--- Part 5. Copper mirror test. The purpose of this specification is to specify a test method for evaluating the aggressiveness of solder to copper by means of the copper mirror test.

--- Part 6. Determination of halide (excluding fluoride) content. The purpose is to specify the use of three quantitative methods for the determination of solder flux

Ionic Halide Content and a Qualitative Method Test Method for the Presence of Ionic Halides in Solder Fluxes.

--- Part 8.Determination of zinc content. The purpose is to specify the test for the determination of zinc content in soldering flux by EDTA titration method method.

--- Part 9.Determination of ammonia content. The purpose of this document is to specify a test method for the determination of ammonia content in solder fluxes by distillation.

--- Part 10.Solder wetting performance spreading test method. The purpose is to specify the use of spreading method to evaluate the wetting performance of solder test method.

--- Part 11.Solubility of flux residues. The purpose is to specify a qualitative method for the evaluation of solder residues in selected solvents Solubility test method.

--- Part 13.Determination of flux splashing. Its purpose is to specify a test method for evaluating the spattering properties of solder fluxes on steel test pieces.

--- Part 14.Evaluation of the adhesiveness of flux residues. The purpose is to specify the use of chalk powder for the evaluation of residues after soldering after soldering. Adhesive test method.

--- Part 15.Copper corrosion test. The purpose is to specify the qualitative evaluation of the surface of copper plates using the copper corrosion test under controlled environmental conditions.

Test method for corrosivity of solder residues.

--- Part 16.Solder wetting properties Wetting balance method. The purpose is to specify the use of wetting balance method to evaluate the wettability of solder capable test method.

--- Part 17.Flux residue surface insulation resistance comb test and electrochemical migration test. The purpose is to specify the use of surface Insulation resistance comb test and electrochemical migration test to evaluate the corrosion of flux residues on the surface of the test piece after soldering method.

Soldering Flux Test Method

Part 9.Determination of ammonia content

1 Scope